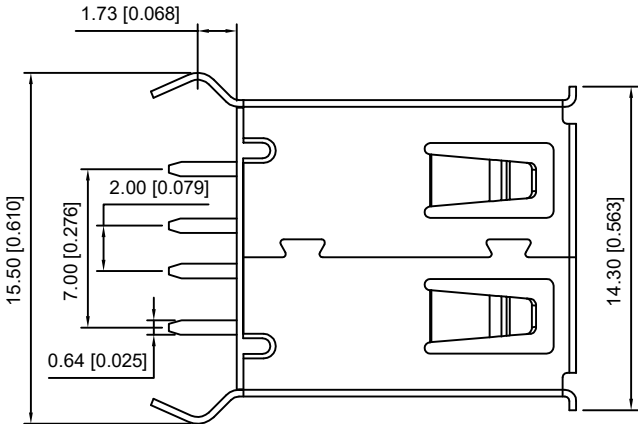
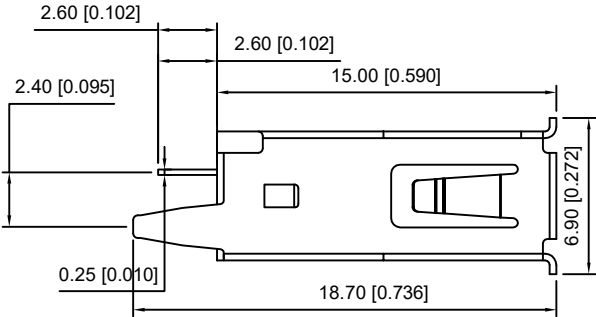
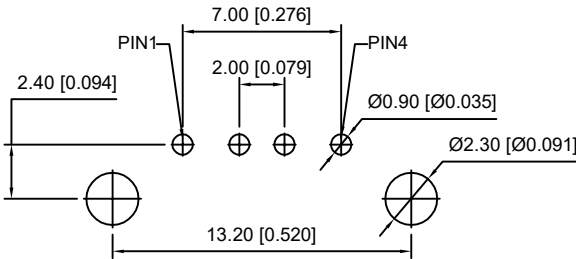
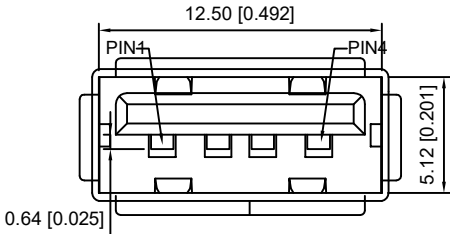




PIN针序号	信号名称
PIN1	VBUS
PIN2	D-
PIN3	D+
PIN4	GND



PCB Layout

Remark 备注:

1.Material 材质:

Shell 外壳:SUS
Terminal 端子:High Grade Copper Alloy
Plastic 塑胶:PBT

2.Plating Specifications 电镀规格:

Shell 外壳:全部区域镀亮镍60μ'
电镀符合"RoHS"标准,
Terminal 端子:镀镍底50u", 接触区域镀金1u",
焊接区镀锡80u"Min.(高温锡)

3.LCP胶芯耐高温245°~260°,PBT胶芯耐高温200°~220°

4.Electrical properties 电气性能:

A.Current 电流:3A MAX
B.Contact Resistance 接触电阻: 50 mΩ. MAX
C.Insulation resistance 绝缘电阻:1000 MΩ MINI 300V/AC
D.Withstand voltage 耐电压: 500V AC 1M

5.Environmental performance 环境性能

A.operating temperature 操作温度: -40°C TO 85°C

6.Mechanical properties 机械特性

A.USB插拔测试:每小时200个周期,插拔5000周期,
功能无损伤.
B.USB插拔力测试:插入力≤3.5kg,拔出力1~3.5kg
测试5次取平均值.插拔3000次后拔出力0.8~3.5kg.
C.盐雾24H,盐雾收集量1.5mL,温度35°,湿度47%.
D.接触PIN针与胶芯保持力≥0.8kg.

7.要求符合USB 2.0标准.

U221-04XN-1XZ19-SS

1: Au 1U"
6: Au 30U"
S: SUS
S: Scrolls
F: Flat
1: PBT
2: PA6T
3: PA9T
4: LCP
B: Black
W: White

物料清单	3	壳子	SUS	T=0.30mm 电镀: Cu≥80u",Ni≥100u"
	2	塑胶	PBT	(PBT耐温260°±5°)
	1	端子	High Grade Copper Alloy	T=0.25 电镀: Ni≥50u"Au:1u"Sn≥80u"
	序号	名称	材质	规格说明

					ANGLAR	±5°
Δx					L≤ 4	±0.2
Δx					4<L≤ 16	±0.3
Δx					16<L≤ 63	±0.4
MARK	DESCRIPTION	DATE	REVISED	APPROVED	L> 63	±0.5
REVISIONS					UNSPECIFIED TOLERANCES	
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DSND		SCALE: N/A	MODEL TYPE: USB 2.0		
DWN		VIEW:	PART NO.:		
CHKD		UNIT: mm/in	DWG NO.: U221-04XN-1XZ19-SS		
APPD		SIZE: A4	WEIGHT	SHEET 1/1	REVISION A0